PRELIMINARY

DIE BONDER

T-3002-PRO

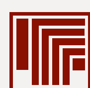
MICRO ASSEMBLY

T-3002-PRO

The T-3002-PRO series is Tresky's most flexible die bonding platform. The systems can run all basic functions as well as the industries most advanced applications by adding a wide range of available options. As with all of Tresky's products, the PRO incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Together with superior ergonomics the PRO platform is the industry's most sophisticated system in its class and with the new PC software even easier to operate.

The T-3002-PRO is equiped with Tresky's die ejector system for pick-up from wafer.

- True Vertical Technology™
- Ultra precise bond-height control
- Unique pick-up from wafer
- Full PC-Control



TRESKY

Dr. TRESKY AG Switzerland Email: tresky@tresky.com www.tresky.com

Advanced multi functional die bonder with superior ergonomic design and programmable, high accuracy Z-Drive and bonding force control.

APPLICATIONS:

Die Attach, Die Sorting, Flip-Chip, 3D Packaging, MEMS, MOEMS, VCSEL, Photonics, Ultrasonic, Thermosonic, RFID, Sensor Assembly, Adhesive Bonding, Eutectic Bonding (AuAu, AuSn, ...), ...

FEATURES AND OPTIONS:

- Programmable Z-Drive with Bonding Force Control
- TRUE VERTICAL TECHNOLOGY™ Z-movement 95mm with 360° Tool rotation; Dispenser, Stamping, Ultrasonic, Scrub, Tool Heating, Pre Form Spindle, ...
- Flip-Chip Ultra Beam Splitter with multi point alignment » 1µm placement accuracy

- Interface for all bonding parameter, temperature profile and video imaging of Beam Splitter Optics, Process Inspection Camera
- XY placement stage supporting: Waffle/Gel - Pack -, Substrate - Holder, various Heating Plates
- Pick-up from Wafer with Tresky's patented die ejector system, especialy suitable for all kind of Si, GaAs and InP dies down to 30µm thickness

TECHNICAL DATA:

XY- Movement (placement stage):	220mm x 220mm (manual)
XY- Movement (wafer stage):	220mm x 220mm (manual)
Z- Movement:	95mm (automatic)
Spindle Rotation:	360°
Bond Force (standard range):	20g - 400g (other force ranges available)
Bond Force (repeatability):	±1g
Z-Measurement resolution:	±0.001mm
Max. PC Board-/ Substrate Size:	400mm x 280mm
Placement accuracy:	±10µm; ±1µm optional (process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	900mm x 800mm x 700mm
Weight:	85kg
Voltage:	110V / 220V

Note: All specifications are subject to change without notice

REPRESENTED BY:

HEADQUATERS

www.tresky.com

Dr. TRESKY AG
Boehnirainstr. 13
CH-8800 Thalwil
Switzerland
Tel.: +41 44 772 1941
Fax: +41 44 772 1945
tresky@tresky.com

TRESKY Corporation
704 Ginesi Drive, Suite 11A
Morganville, NJ 07751
USA
Tel.: +1 732 536 8600
Fax: +1 732 536 0495
sales@tresky.com